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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



### Features

- Excellent thermal stability
- Common source configuration
- Broadband performances  $P_{OUT} = 2\text{ W}$  with 13 dB gain @ 870 MHz
- Plastic package
- ESD protection
- Supplied in tape and reel
- In compliance with the 2002/95/EC european directive

### Description

The PD84002 is a common source N-channel, enhancement-mode lateral Field-Effect RF power transistor. It is designed for high gain, broad band commercial and industrial applications. It operates at 7 V in common source mode at frequencies of up to 1 GHz.

PD84002's superior gain and efficiency makes it an ideal solution for portable radio and UHF RFID reader.

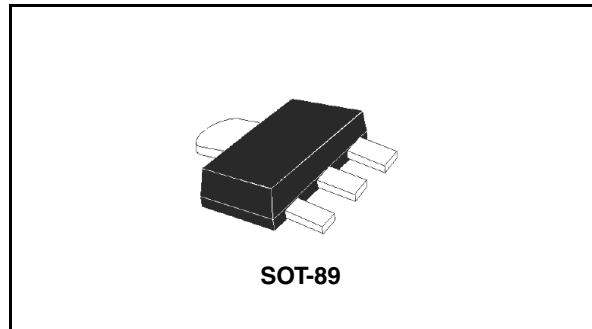


Figure 1. Pin connection

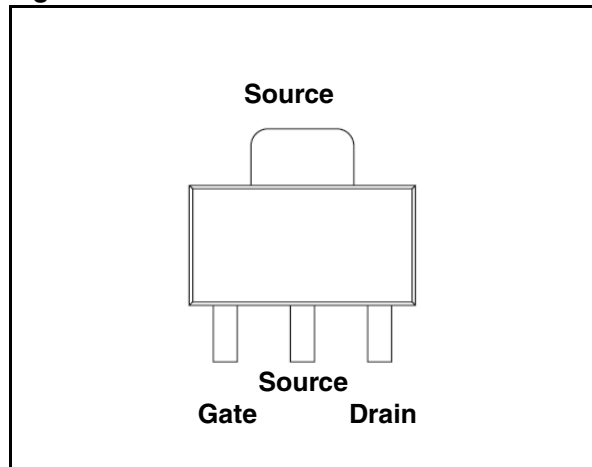


Figure 2. Device summary

Order code	Marking	Package	Packaging
PD84002	8402	SOT-89	Tape and reel

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# 1 Electrical data

## 1.1 Maximum ratings

Table 1. Absolute maximum ratings ( $T_{CASE} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	25	V
$V_{GS}$	Gate-source voltage	-0.5 to +15	V
$I_D$	Drain current	2	A
$P_{DISS}$	Power dissipation	6	W
$T_J$	Max. operating junction temperature	150	$^{\circ}C$
$T_{STG}$	Storage temperature	-65 to +150	$^{\circ}C$

## 1.2 Thermal data

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thJC}$	Junction - case thermal resistance	21	$^{\circ}C/W$

## 2 Electrical characteristics

$$T_{CASE} = +25\text{ }^{\circ}\text{C}$$

### 2.1 Static

Table 3. Static

Symbol	Test conditions		Min	Typ	Max	Unit
$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	$V_{GS} = 5\text{ V}$	$V_{DS} = 0\text{ V}$			1	$\mu\text{A}$
$V_{GS(Q)}$	$V_{DS} = 7.5\text{ V}$	$I_D = 100\text{ mA}$		3.9		V
$V_{DS(ON)}$	$V_{GS} = 10\text{ V}$	$I_D = 0.25\text{ A}$		0.27		V
$C_{ISS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 7.5\text{ V}$		16		pF
$C_{OSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 7.5\text{ V}$		16		pF
$C_{RSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 7.5\text{ V}$		1.2		pF

### 2.2 Dynamic

Table 4. Dynamic

Symbol	Test conditions	Min	Typ	Max	Unit
$P_{OUT}$	$V_{DD} = 7.5\text{ V}$ , $I_{DQ} = 100\text{ mA}$ , $P_{IN} = 0.1\text{ W}$ , $f = 870\text{ MHz}$	2			W
$G_{PS}$	$V_{DD} = 7.5\text{ V}$ , $I_{DQ} = 100\text{ mA}$ , $P_{OUT} = 2\text{ W}$ , $f = 870\text{ MHz}$	13	15		dB
$N_D$	$V_{DD} = 7.5\text{ V}$ , $I_{DQ} = 100\text{ mA}$ , $P_{OUT} = 2\text{ W}$ , $f = 870\text{ MHz}$	60	65		%
Load mismatch	$V_{DD} = 7.5\text{ V}$ , $I_{DQ} = 100\text{ mA}$ , $P_{OUT} = 2\text{ W}$ , $f = 870\text{ MHz}$ All phase angles	20:1			VSWR

### 2.3 ESD protection characteristics

Table 5. ESD protection characteristics

Test conditions	Class
Human body model	2
Machine model	M3

### 2.4 Moisture sensitivity level

Table 6. Moisture sensitivity level

Test methodology	Rating
J-STD-020B	MSL 3

### 3 Impedances

Figure 3. Impedances

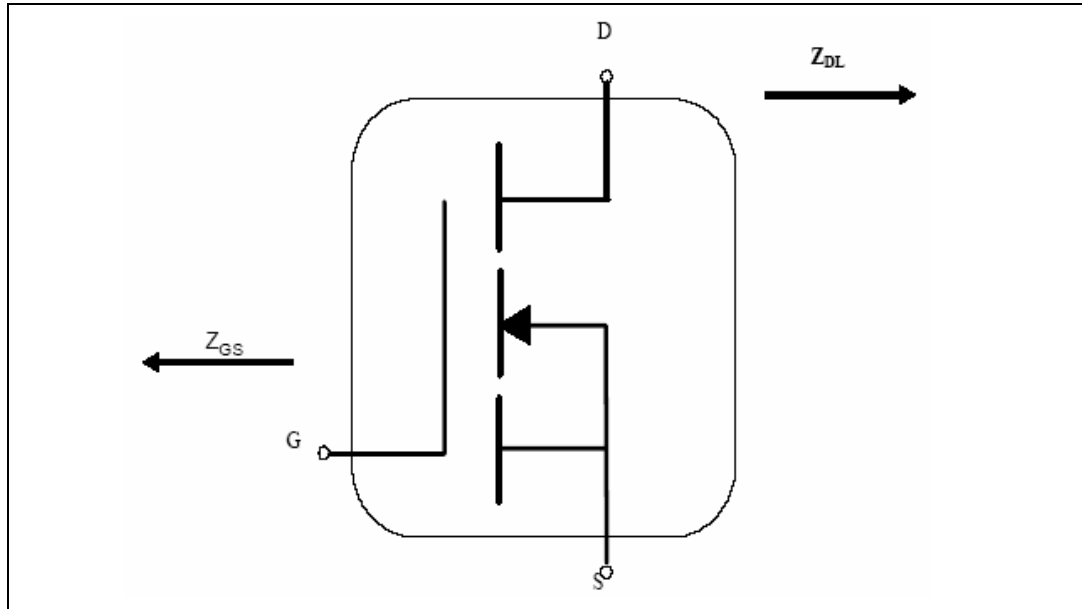


Table 7. Impedances

F(MHz)	$Z_{GS}$	$Z_{DL}$
860	$1,80 + j 7,79$	$3,88 + j 2,41$
870	$1,84 + j 7,96$	$3,89 + j 2,69$
880	$1,83 + j 8,01$	$4,01 + j 2,96$
890	$1,76 + j 8,11$	$4,17 + j 3,16$
900	$1,70 + j 8,20$	$4,27 + j 3,32$
910	$1,63 + j 8,30$	$4,37 + j 3,40$
920	$1,57 + j 8,48$	$4,41 + j 3,46$
930	$1,43 + j 8,64$	$4,36 + j 3,51$
940	$1,41 + j 8,83$	$4,28 + j 3,51$

# 4 DC curves

Figure 4. DC output characteristics

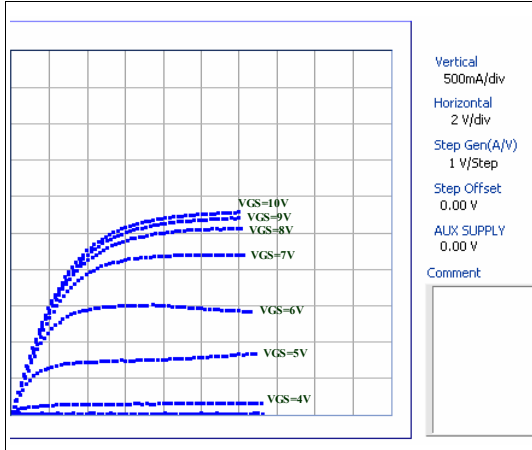


Figure 5. ID vs VGS

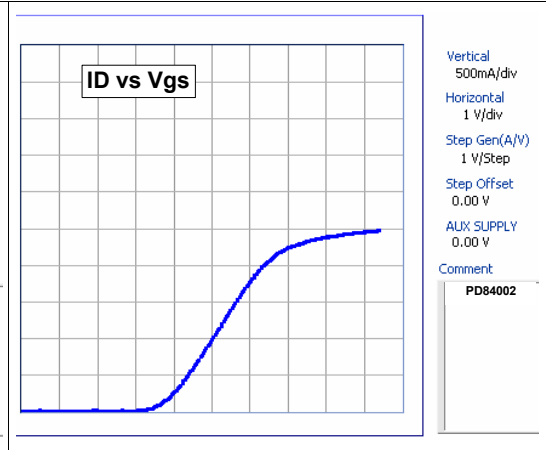
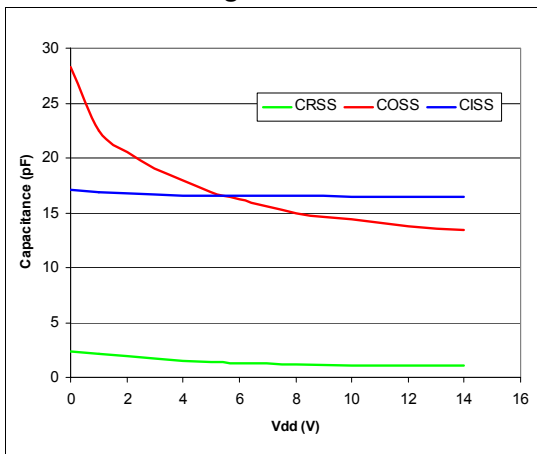
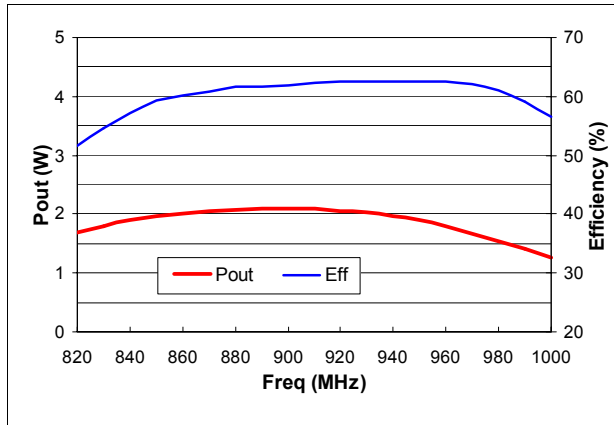


Figure 6. Capacitances vs drain voltage

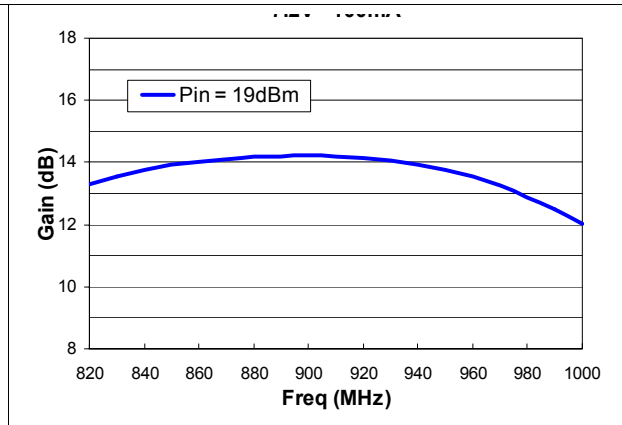


## 5 RF curves

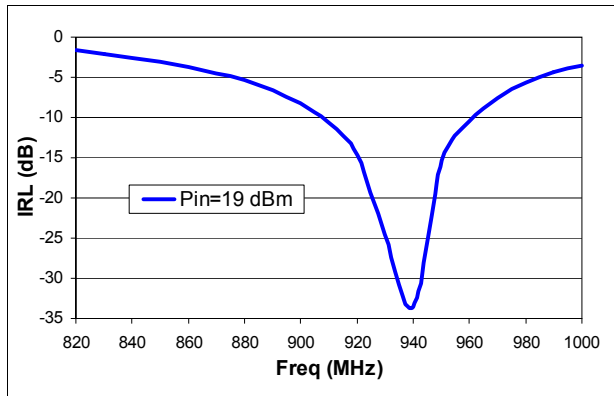
**Figure 7. Output power and efficiency vs frequency 7.2 V / 100 mA / Pin = 19 dBm**



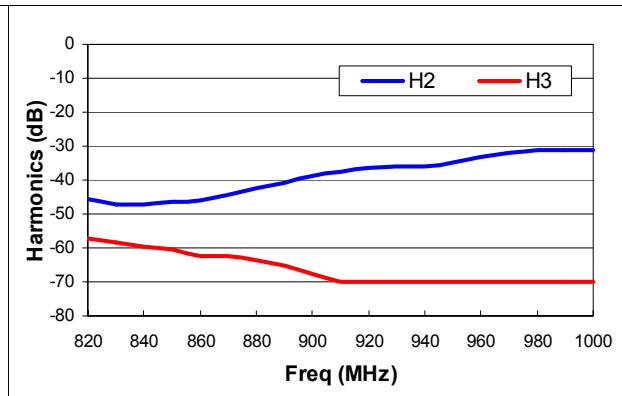
**Figure 8. Gain vs frequency 7.2 V - 100 mA**



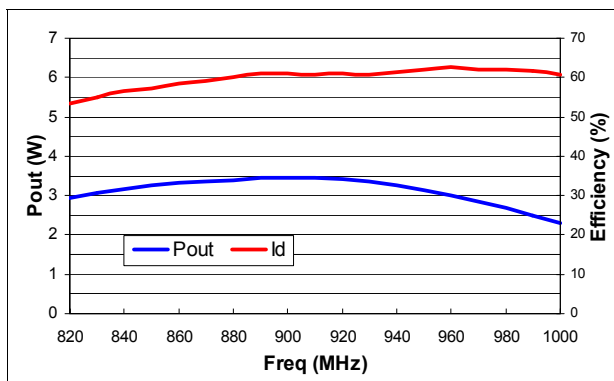
**Figure 9. Input return loss vs frequency 7.2 V / 100 mA**



**Figure 10. Harmonics vs frequency 7.2 V / 100 mA**



**Figure 11. Output power and efficiency vs frequency 9 V / 100 mA / Pin = 22 dBm**





## 6 Schematic and BOM

Figure 12. Schematic

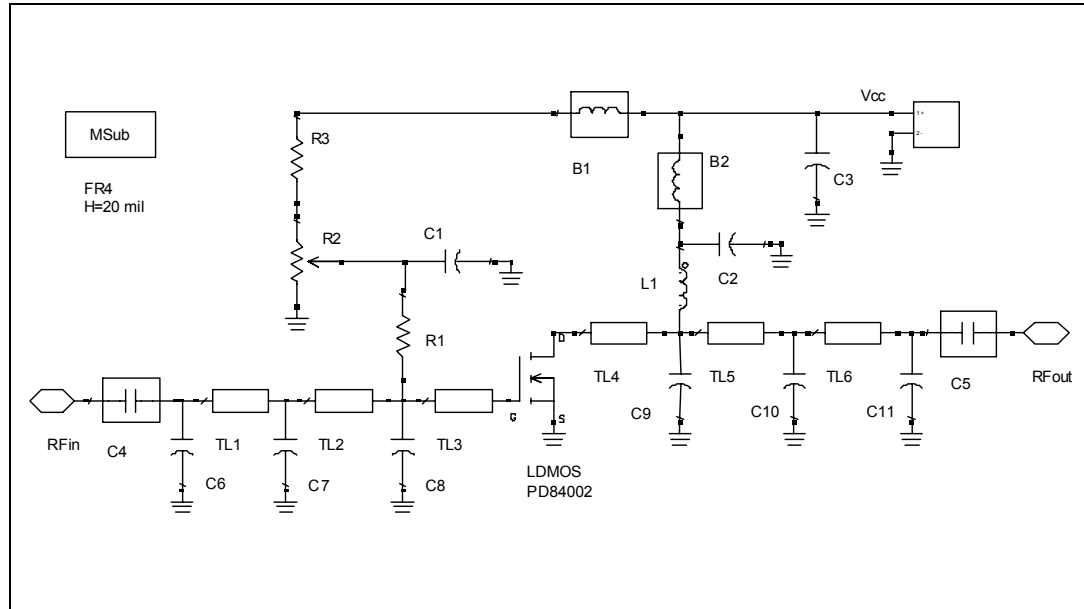


Table 8. Components part list

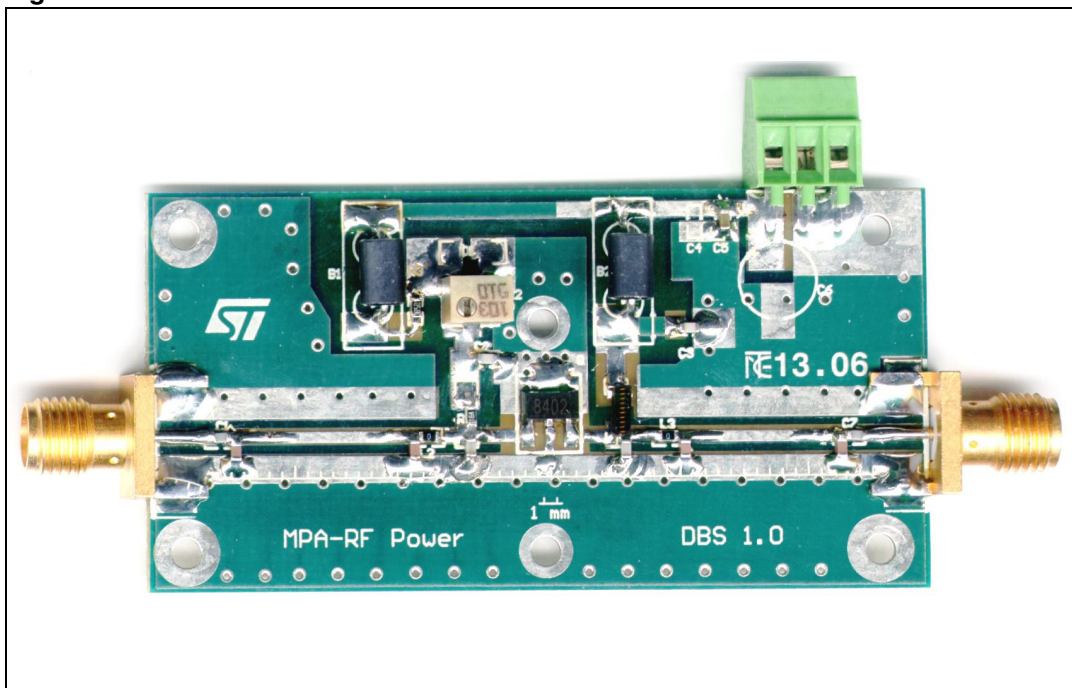
Component ID	Description	Value	Case size	Manufacturer	Part Code
B1	Ferrite Bead			Panasonic	EXCELDR35C
B2	Ferrite Bead			Panasonic	EXCELDR35C
C1, C2	Capacitor	120 pF	0603	Murata	GRM39-C0G121J50D500
C3	Capacitor	1 uF	0603	Murata	GRM39-X5R105K16D52K
C4, C5	Capacitor	39 pF	0603	Murata	GRM39-C0G390J50D500
C6, C10	Capacitor	3.3 pF	0603	Murata	GRM39-C0G3R3C50Z500
C7	Capacitor	8.2 pF	0603	Murata	GRM39-C0G8R2D50Z500
C8	Capacitor	22 pF	0603	Murata	GRM39-C0G220J50D500
C9	Capacitor	12 pF	0603	Murata	GRM39-C0G120J50D500
C11	Capacitor	2.7 pF	0603	Murata	GRM39-C0G2R7C50Z500
L1	Inductor	12.55 nH		Coilcraft	1606-10
R1	Resistor	150 Ω	0603	Tyco electronics	
R2	Potentiometer	10 KΩ		Bourns electronics	3214W-1-103E
R3	Resistor	1 K	0603	Tyco electronics	01623440-1

**Table 8. Components part list (continued)**

Component ID	Description	Value	Case size	Manufacturer	Part Code
TL1	Transmission line	W=0.92 mm	L=13.6 mm		
TL2	Transmission line	W=0.92 mm	L=3.5 mm		
TL3	Transmission line	W=0.92 mm	L=4.2 mm		
TL4	Transmission line	W=0.92 mm	L=3.8 mm		
TL5	Transmission line	W=0.92 mm	L=3.7 mm		
TL6	Transmission line	W=0.92 mm	L=11.3 mm		
RF in, RF out	SMA-CONN	50 Ω	60 mils	JOHNSON	142-0701-801
PD84002	LDMOS			STMicroelectronics	PD84002
Board	FR-4 THk=0.020" 2OZ Cu Both Sides				

## 7 Photo

**Figure 13. Photo**



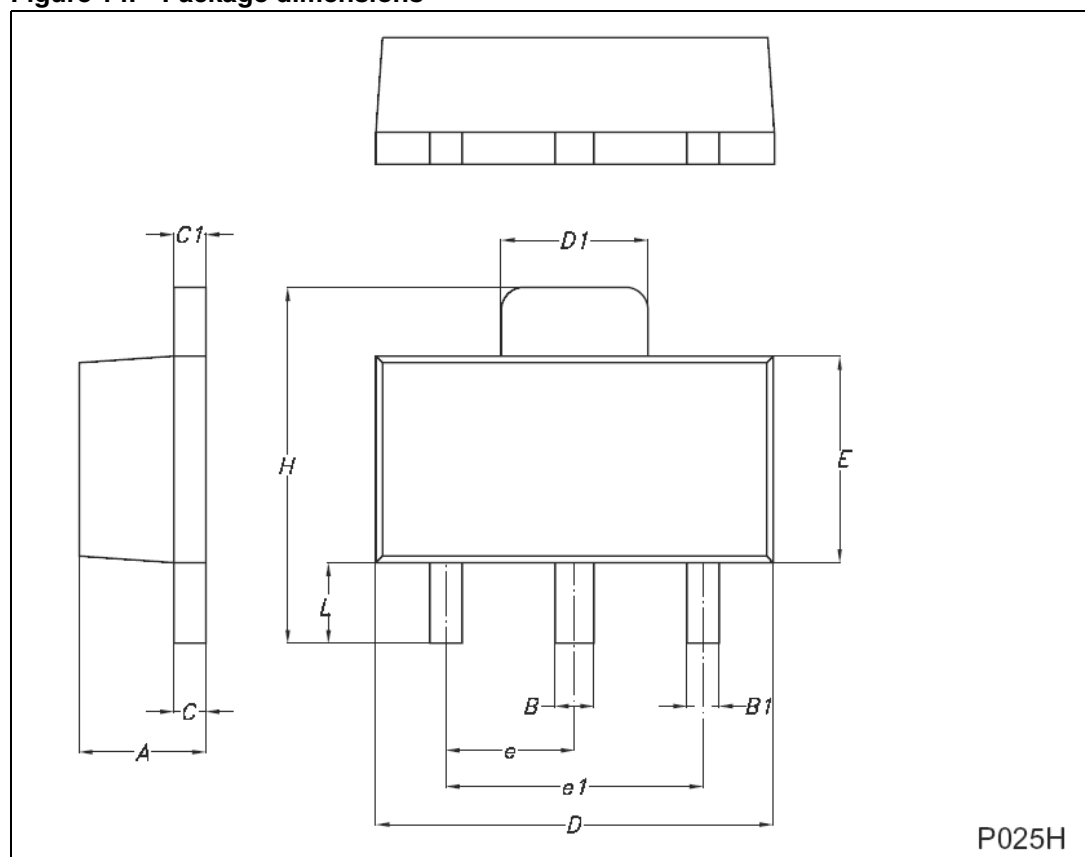
## 8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

**Table 9. SOT-89 mechanical data**

Dim.	mm.			Inch		
	Min	Typ	Max	Min	Typ	Max
A	1.4		1.6	55.1		63.0
B	0.44		0.56	17.3		22.0
B1	0.36		0.48	14.2		18.9
C	0.35		0.44	13.8		17.3
C1	0.35		0.44	13.8		17.3
D	4.4		4.6	173.2		181.1
D1	1.62		1.83	63.8		72.0
E	2.29		2.6	90.2		102.4
e	1.42		1.57	55.9		61.8
e1	2.92		3.07	115.0		120.9
H	3.94		4.25	155.1		167.3
L	0.89		1.2	35.0		47.2

**Figure 14. Package dimensions**

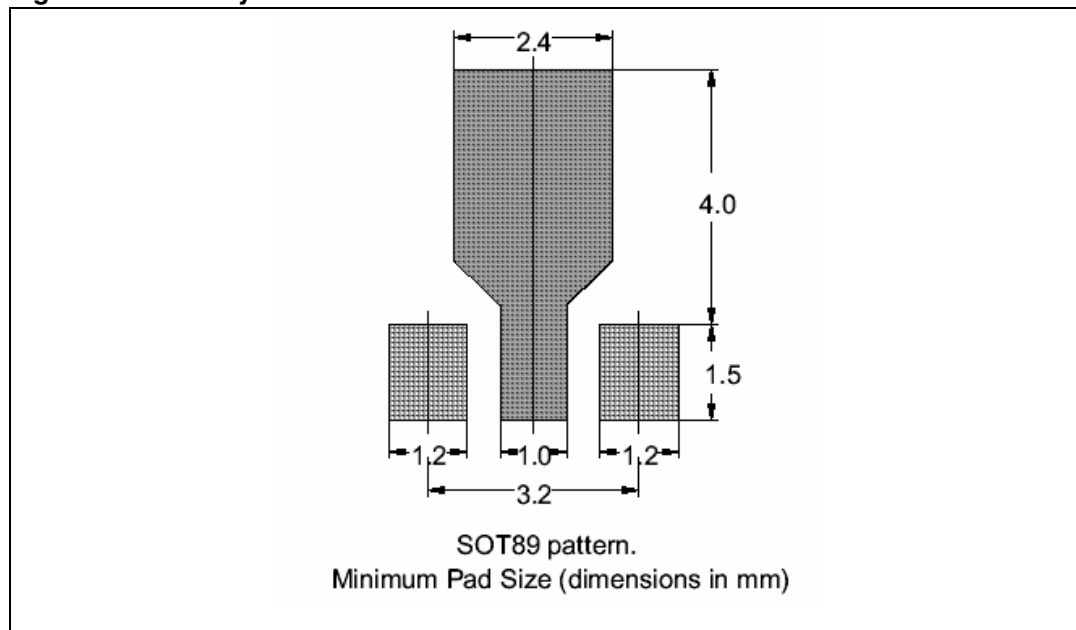


### 8.1 Thermal pad and via design

Thermal vias are required in the PCB layout to effectively conduct heat away from the package. The via pattern has been designed to address thermal, power dissipation and electrical requirements of the device.

The via pattern is based on thru-hole vias with 0.203mm to 0.330mm finished hole size on a 0.5mm to 1.2mm grid pattern with 0.025 plating on via walls. If micro vias are used in a design, it is suggested that the quantity of vias be increased by a 4:1 ratio to achieve similar results.

**Figure 15. Pad layout details**



## 8.2 Soldering profile

Figure 16 shows the recommended solder for devices that have Pb-free terminal plating and where a Pb-free solder is used.

**Figure 16. Recommended solder profile**

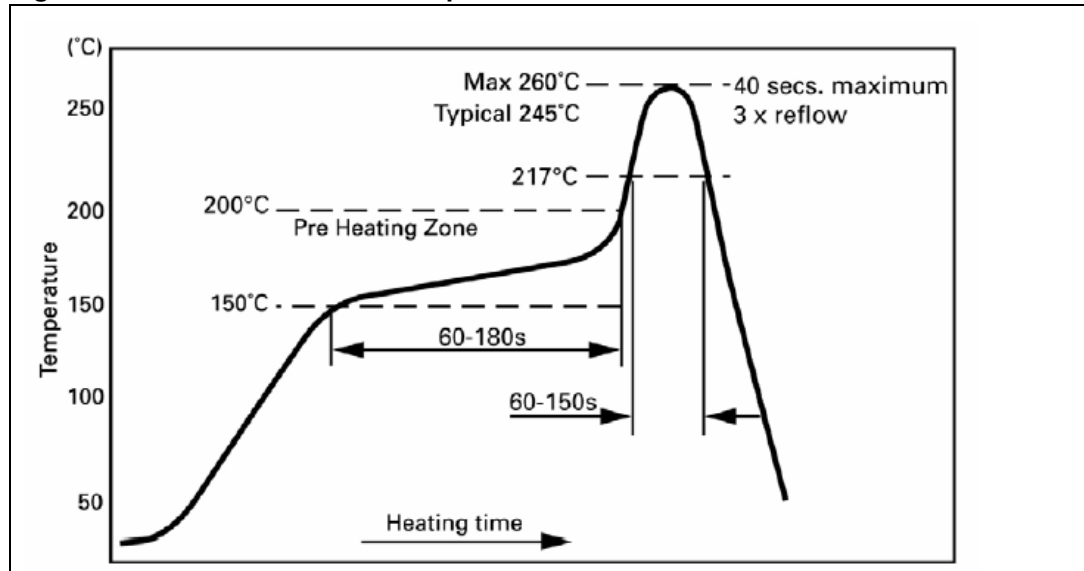


Figure 17 shows the recommended solder for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

**Figure 17. Recommended solder profile for leaded devices**

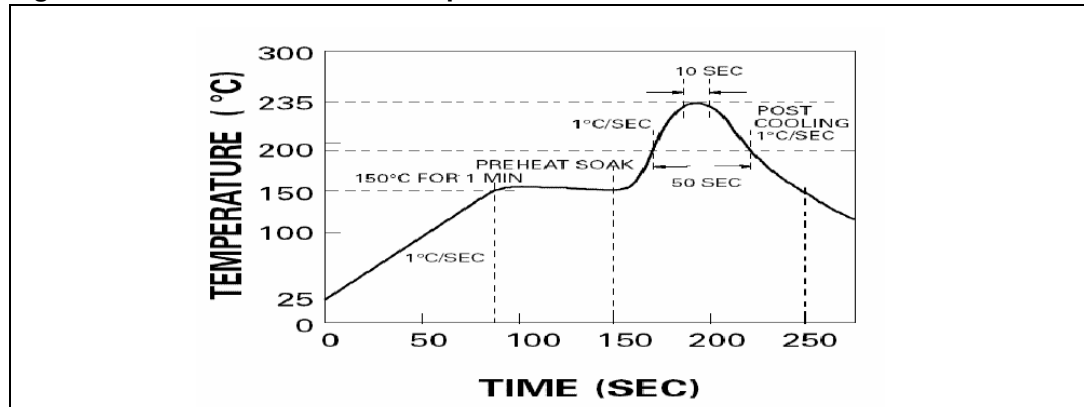
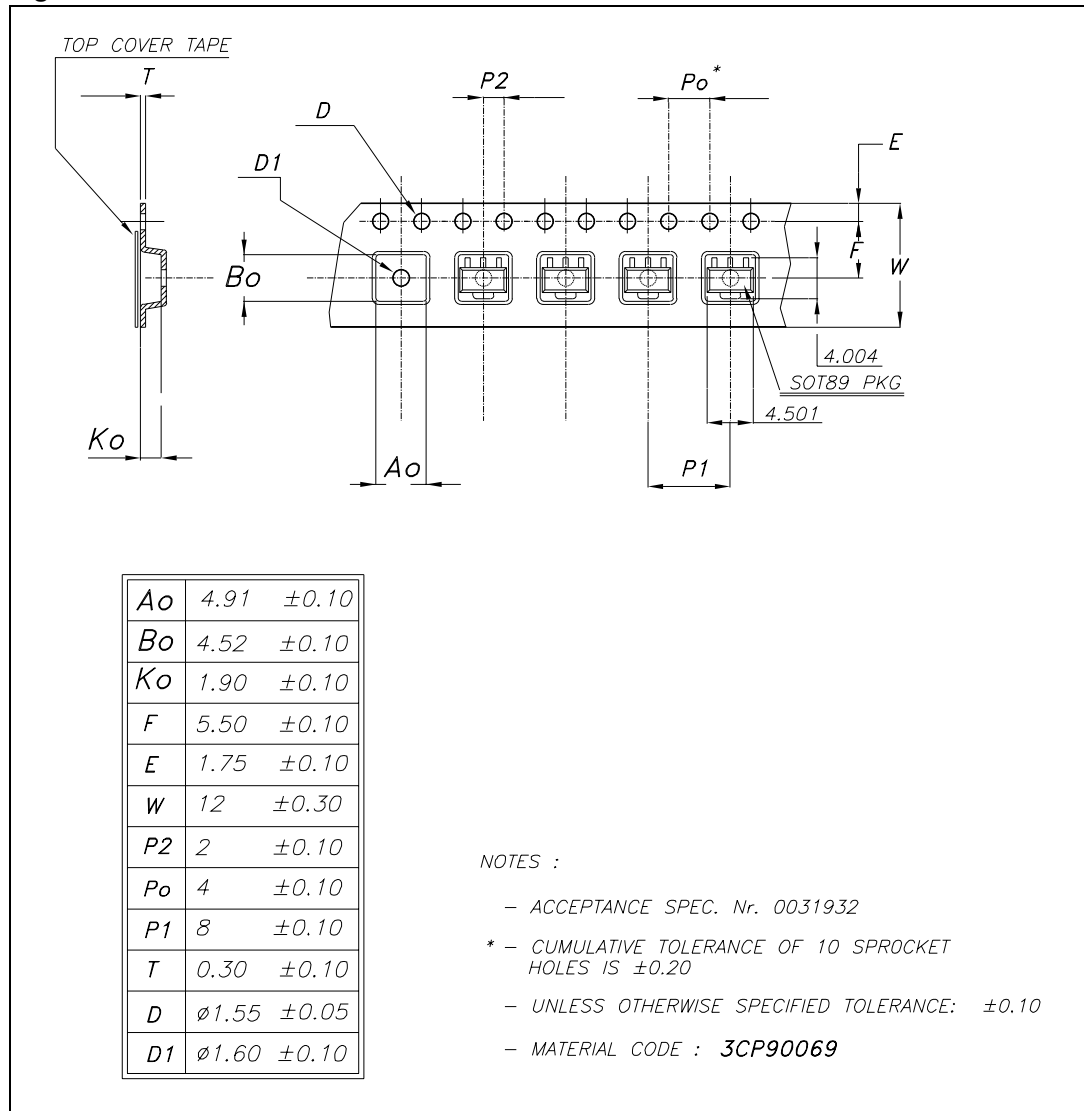


Figure 18. Reel information



## 9 Revision history

**Table 10. Document revision history**

Date	Revision	Changes
05-Dec-2007	1	Initial release.



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